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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/661,100	09/12/2003	Gurtej S. Sandhu	303.869US1 6569		
75	90 06/09/2005		EXAM	INER	
Schwegman Lundberg Woessner & Kluth, P.A Attn:Viet V. Tong			ZARNEKE,	ZARNEKE, DAVID A	
P.O BOX 2938			ART UNIT	PAPER NUMBER	
mINNEAPOLIS, MN 55402			2891		

DATE MAILED: 06/09/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)			
Office Action Summary		10/661,100	SANDHU ET AL.			
		Examiner	Art Unit			
		David A. Zarneke	2891			
The MAILIN Period for Reply	IG DATE of this communication ap	pears on the cover sheet with the c	orrespondence address			
THE MAILING DA - Extensions of time may after SIX (6) MONTHS - If the period for reply si - Failure to reply within the company received by the company to the company received by the company rece	TATUTORY PERIOD FOR REPL TE OF THIS COMMUNICATION. To be available under the provisions of 37 CFR 1.1 The from the mailing date of this communication. The provisions of 37 CFR 1.1 The provisions of 37 CFR 1.704 The provisions	36(a). In no event, however, may a reply be ting you within the statutory minimum of thirty (30) day will apply and will expire SIX (6) MONTHS from a cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. 8 133)			
Status						
1) Responsive	to communication(s) filed on 25 A	<u>pril 2005</u> .				
2a) ☐ This action i	s FINAL . 2b)⊠ This	action is non-final.				
3) Since this a						
closed in ac	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claim	s					
4)⊠ Claim(s) <u>1-6</u>	4)⊠ Claim(s) <u>1-66</u> is/are pending in the application.					
4a) Of the at	4a) Of the above claim(s) <u>1-49</u> is/are withdrawn from consideration.					
	Claim(s) is/are allowed.					
	Claim(s) <u>50-66</u> is/are rejected.					
	is/are objected to.	a alaatian na arrigana ant				
	are subject to restriction and/o	r election requirement.				
Application Papers						
9) The specification is objected to by the Examiner.						
	10)☐ The drawing(s) filed on is/are: a)☐ accepted or b)☐ objected to by the Examiner.					
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).						
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d). 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.						
TI) THE GALL OF	decidiation is objected to by the Ex	raminer. Note the attached Office	Action or form P1O-152.			
Priority under 35 U.S	.C. § 119					
a)□ All b)□	ment is made of a claim for foreign Some * c)⊡ None of: ed copies of the priority document		⊢(d) or (f).			
2. Certified copies of the priority documents have been received in Application No						
3. Copies of the certified copies of the priority documents have been received in this National Stage						
application from the International Bureau (PCT Rule 17.2(a)).						
* See the attached detailed Office action for a list of the certified copies not received.						
Attachment(s)						
1) Notice of References Cited (PTO-892) 4) Interview Summary (PTO-413)						
2) Notice of Draftsperso	n's Patent Drawing Review (PTO-948)	Paper No(s)/Mail Da	ate			
Information Disclosur Paper No(s)/Mail Date	e Statement(s) (PTO-1449 or PTO/SB/08) e 13-76-04, 4-39-05	5) Notice of Informal P	atent Application (PTO-152)			

DETAILED ACTION

Election/Restrictions

Applicant's election without traverse of Group II, claims 50-66 in the reply filed on 4/25/05 is acknowledged.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

nitride, and fluorine doped with carbide (7, 25+).

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 50 and 52 are rejected under 35 U.S.C. 102(e) as being clearly anticipated by Fairburn et al. US Patent 6,573,030.

Fairburn (figures 2A-E) teaches a method comprising:

forming a device structure [250] over the substrate [200]; and

forming a masking structure over the device structure, the masking structure including
an amorphous carbon layer [204] and a cap layer [206], the cap layer including a

material selected from a group consisting of boron carbide, boron nitride, silicon
carbide, silicon nitride, fluoride films, fluorine doped with oxide, fluorine doped with

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Regarding claim 52, Fairburn teaches the amorphous carbon layer is transparent in visible light range.

Claims 53, 54, and 56 are rejected under 35 U.S.C. 102(e) as being clearly anticipated by Fairburn et al. US Patent 6,573,030.

Fairburn teaches a method comprising:

forming a device structure [250] on a substrate [200];

forming an amorphous carbon layer [204] over the device structure;

forming a non-oxide cap layer [206] over the amorphous carbon layer;

patterning the non-oxide cap layer to produce a patterned non-oxide cap layer (figure 2D & 7, 45+); and

using the patterned non-oxide cap layer as a mask to pattern the amorphous carbon layer (figure 2D & 7, 45+).

Regarding claim 54, Fairburn teaches the cap layer includes one of boron carbide, boron nitride, silicon carbide, silicon nitride, fluoride films, fluorine doped with oxide, fluorine doped with nitride, and fluorine doped with carbide (7, 25+).

With respect to claim 56, Fairburn teaches the amorphous carbon layer is formed by deposition (5, 61+).

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the

invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

The factual inquiries set forth in *Graham* v. *John Deere Co.*, 383 U.S. 1, 148 USPQ 459 (1966), that are applied for establishing a background for determining obviousness under 35 U.S.C. 103(a) are summarized as follows:

- 1. Determining the scope and contents of the prior art.
- 2. Ascertaining the differences between the prior art and the claims at issue.
- 3. Resolving the level of ordinary skill in the pertinent art.
- 4. Considering objective evidence present in the application indicating obviousness or nonobviousness.

This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).

Claim 51 is rejected under 35 U.S.C. 103(a) as being unpatentable over Fairburn et al. US Patent 6,573,030, as applied to claim 50 above.

Though Fairburn fails to teach the material of the cap layer is in situ deposited over the amorphous carbon layer, it would have been obvious to form the cap layer in situ because this would speed up the processing time. The use of conventional methods to perform there known functions in a conventional process is obvious (MPEP 2144.07).

Claims 55, 57 and 58 are rejected under 35 U.S.C. 103(a) as being unpatentable over Fairburn et al. US Patent 6,573,030, as applied to claim 53 above.

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Regarding claim 55, though Fairburn fails to teach the carbon layer has an absorption coefficient between about 0.15 and 0.001 at a wavelength of 633 nanometers, it would have been obvious to one ordinary skill in the art at the time of the invention to optimize the absorption coefficient through routine experimentation in order to tune the optical properties and the etch selectivity, as taught by Fairburn (6, 31+) (MPEP 2144.05).

With respect to claim 57, though Fairburn fails to teach the material of the cap layer is in situ deposited over the amorphous carbon layer, it would have been obvious to form the cap layer in situ because this would speed up the processing time. The use of conventional methods to perform there known functions in a conventional process is obvious (MPEP 2144.07).

As to claim 58, Fairburn teaches the amorphous carbon layer is formed by a chemical vapor deposition process (4, 18+).

Claims 59-62 are rejected under 35 U.S.C. 103(a) as being unpatentable over Fairburn et al. US Patent 6,573,030.

Fairburn teaches a method comprising:

forming device structure [250] on a substrate;

forming masking structure [204, 206 & 208] over the device structure, the masking structure includes an amorphous carbon layer [204] and a cap layer [206], the cap layer including non-oxide materials;

patterning the masking structure to form a patterned masking structure (figure 2D);

etching the device structure using the patterned masking structure as a mask; and removing the patterned masking structure (figure 2E).

Though Fairburn fails to teach the device structure has a gate structure and etching to form a portion of a memory cell, when considering Fairburn does teach the substrate structure is the substrate [200] with other material layers thereon (6, 60+) such as silicides, metals or other materials (7, 6+), one of ordinary skill would know that this could conventionally apply to the formation of a gate structure used in the formation of a memory cell. The use of conventional materials to perform there known functions in a conventional process is obvious (MPEP 2144.07).

Regarding claim 60, Fairburn teaches patterning the masking structure includes: using a patterned photoresist layer [208] as a mask to pattern the cap layer to form a patterned cap layer; and using at least one of the patterned cap layer and the patterned photoresist layer to pattern the amorphous carbon layer (figure 2D & 7, 45+).

As to claim 61, though Fairburn, which teaches using an appropriate chemical etchant (7, 45+), fails to specifically teach the patterning the cap layer is performed by oxygen plasma etch process, it would have been obvious to one of ordinary skill to optimize the etchant to be an oxygen plasma etch (MPEP 2144.05).

In re claim 62, though Fairburn, which teaches using an oxygen plasma process (7, 51+), fails to specifically teach removing the patterned amorphous carbon is performed using an oxygen plasma process with one of CF.4 and H2, it would have

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been obvious to one of ordinary skill to optimize the oxygen plasma etch to include one of CF.4 and H2 because these are conventionally known in the art to be added to oxygen plasma etches. The use of conventional materials to perform there known functions in a conventional process is obvious (MPEP 2144.07).

Claims 63-66 are rejected under 35 U.S.C. 103(a) as being unpatentable over Fairburn et al. US Patent 6,573,030.

Fairburn teaches a method comprising:

placing a wafer in a chamber, the wafer including at least one die having a substrate [200] and a device structure [250] formed over the substrate;

forming an amorphous carbon layer [204] over the device structure; and forming a cap layer [206] over the amorphous carbon layer, the cap layer including a material selected from a group consisting of boron carbide, boron nitride, silicon carbide, silicon nitride, fluoride films, fluorine doped with oxide, fluorine doped with nitride, and fluorine doped with carbide (7, 25+).

Though Fairburn fails to teach a wafer in a chamber, the wafer including at least one die having a substrate and a device structure formed over the substrate, when considering Fairburn does teach the substrate [200] refers to any workpiece on which processing is performed (6, 63+), one of ordinary skill would know that this could conventionally apply to the formation of a gate structure used in the formation of a memory cell. The use of conventional materials to perform there known functions in a conventional process is obvious (MPEP 2144.07).

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Further, though Fairburn doesn't explicitly teach using a chamber, the teaching of depositing layers implicitly teaches using a chamber because how else would one deposit layers except in a chamber (MPEP 2144.01).

Regarding claim 64, though Fairburn fails to teach the material of the cap layer is in situ deposited over the amorphous carbon layer, it would have been obvious to form the cap layer in situ because this would speed up the processing time. The use of conventional methods to perform there known functions in a conventional process is obvious (MPEP 2144.07).

Regarding claim 65, Fairburn teaches the amorphous carbon layer is transparent in visible light range.

As to claim 66, Fairburn teaches the chamber is a plasma enhanced vapor chemical deposition chamber (2, 38+).

Conclusion

The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. US Patents 6,653,735; 6,884,733; 6,875,664; 6,803,313; and 6,825,114 are all cited as teaching the inventions that are 102(e) references.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to David A. Zarneke whose telephone number is (571)-272-1937. The examiner can normally be reached on M-Th 7:30 AM-6 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, William Baumeister can be reached on (571)-272-1712. The fax phone

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number for the organization where this application or proceeding is assigned is 703-872-9306.

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David A. Zarneke

June 5, 2005